

IN THE CLAIMS:

Please cancel claim 15 in its entirety without prejudice nor disclaimer of the subject matter set forth therein.

Please amend claims 12 and 21 as follows.

1-11. (Canceled)

12. (Currently Amended) A semiconductor device comprising:

a wiring board;

a first semiconductor chip and a second semiconductor chip, each of which has a circuitry side and a non-circuitry side that face each other vertically and each of which is electrically connected to the wiring board via raised electrodes, the circuitry side of the first and second chips facing the principal surface of the wiring board; and

a third semiconductor chip, which has a circuitry side and a non-circuitry side that face each other vertically and which includes external electrodes on the circuitry side thereof,

wherein the non-circuitry ~~sides~~ ~~side~~ of the third semiconductor ~~chips~~ are ~~chip~~ ~~is~~ secured to the non-circuitry side of the first semiconductor chip and the non-circuitry side of the second semiconductor chip,

wherein the external electrodes of the third semiconductor chip are connected to the wiring board via metal fine wires, and

wherein the external electrodes are disposed so as not to overlap with the raised electrodes.

13. (Previously Presented) The device of claim 12, wherein the first semiconductor chip, the second semiconductor chip and third semiconductor chip have a thickness of 300 μ m or lower.

14. (Previously Presented) The device of claim 12, wherein the external electrodes are provided on the inner side of the second semiconductor chip and the third semiconductor chip with respect to the raised electrodes.

15. (Canceled)

16. (Previously Presented) The device of claim 12, wherein the raised electrodes and the wiring board are secured to each other with a conductive adhesive.

17. (Previously Presented) The device of claim 12, wherein the raised electrodes and the wiring board are secured to each other with a low-melting metal.

18. (Previously Presented) The device of claim 12, wherein the raised electrodes are in direct contact with the principle surface of the wiring board.

19. (Previously Presented) The device of claim 12, wherein the first semiconductor chip, the second semiconductor chip and third semiconductor chip are LSI chips.

20. (Previously Presented) The device of claim 19, wherein the combination of chips is a logic chip and a memory chip.

21. (Currently Amended) The device of claim 12, wherein a width of the third semiconductor chip is narrower than a distance between a lateral face of the first semiconductor chip and a lateral face of the second semiconductor chip that are furthest apart from each other among lateral faces of the first and second semiconductor chips ~~side faces of the second and third semiconductor chips are on the inner side of the side faces of the first semiconductor chip.~~